

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application: Rajeev Joshi et al.  Serial No.: 10/731,453  Filed: December 9, 2003  For: WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME	Confirmation No. 4432  Group Art Unit: 2891  Office: Zarnecke, David A.
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Mail Stop Non-Final Response  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT AND REQUEST FOR RECONSIDERATION**

In response to the Office Action mailed July 16, 2008, Applicant requests reconsideration of this application in light of the following amendments and remarks.

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks** begin on page 7 of this paper.